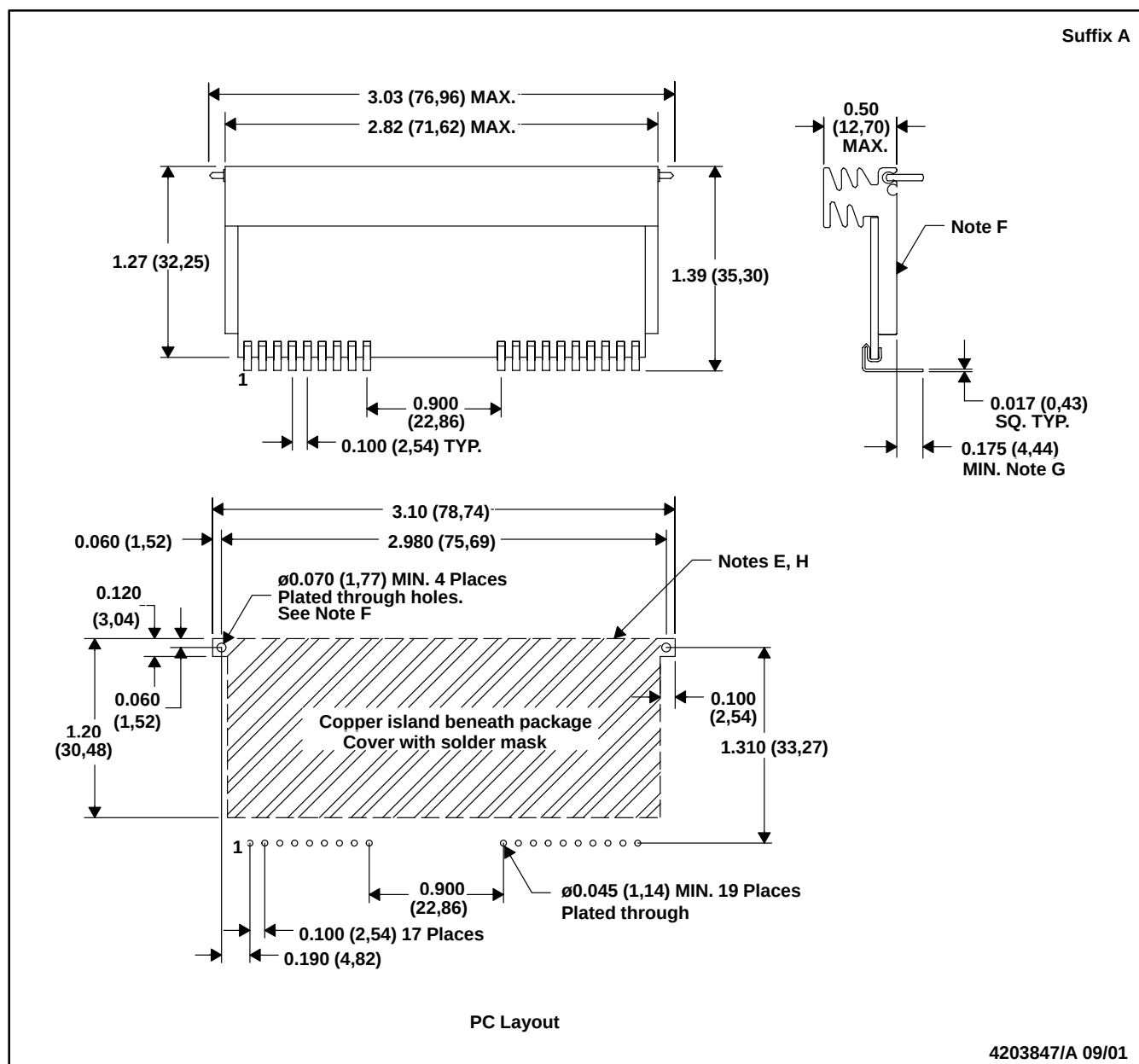


EHH (R-MSIP-T19)

METAL SINGLE-IN-LINE MODULE



- NOTES: A. All linear dimensions are in inches (mm).
 B. This drawing is subject to change without notice.
 C. 2 place decimals are ± 0.030 (± 0.76 mm).
 D. 3 place decimals are ± 0.010 (± 0.25 mm).
 E. Recommended mechanical keep out area.
 F. The heatsink is electrically uncommitted. The recommended connection is to secondary ground plane.
 G. Electrical pin length mounted on printed circuit board, from seating plane to pin end.
 H. Case outline reference.

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